Refine Search

Search Results -

Terms	Documents
L8 and ((opening$ or via$ or hole$) near6 (("bonding egent") near5 through))	0

US Pre-Grant Publication Full-Text Database
US Patents Full-Text Database
US OCR Full-Text Database
EPO Abstracts Database
JPO Abstracts Database
Derwent World Patents Index
IBM Technical Disclosure Bulletins

Search Forms
Search **Database:**

Search Results

Help

User Searches

Preferences
Search:

Logout

L16

[Refine Search]

[Recall Text ⬍]   [Clear]   [Interrupt]

Search History

DATE: Thursday, November 18, 2004   Printable Copy   Create Case

Set Name side by side	Query	Hit Count	Set Name result set
	DB=USPT; PLUR=YES; OP=OR		
L16	L8 and ((opening$ or via$ or hole$) near6 (("bonding egent") near5 through))	0	L16
	DB=TDBD; PLUR=YES; OP=OR		
L15	L14	0	L15
	DB=DWPI; PLUR=YES; OP=OR		
L14	L13	0	L14
	DB=JPAB; PLUR=YES; OP=OR		
L13	L12	0	L13
	DB=EPAB; PLUR=YES; OP=OR		
L12	L11	0	L12
	DB=USOC; PLUR=YES; OP=OR		
L11	L10	0	L11
	DB=USPT; PLUR=YES; OP=OR		

h   e b   b   cg b   e e   ch

L10	L8 and ((opening$ or via$ or hole$) same (("bonding egent") near6 extend$))	0	L10
L9	L8 and ((opening$ or via$ or hole$) near6 "bonding egent")	0	L9
L8	(lid or frame) and (die or chip)	100080	L8
L7	L3 and (("opening" or hole) near5 "bonding agent")	0	L7
L6	L3 and ("opening" near5 "bonding agent").	0	L6
L5	L3 and ("opening" near5 "bnding agent")	0	L5
L4	L3 and ("through hole" near5 "bnding agent")	0	L4
L3	L2 and (lid$ or frame)	44	L3
L2	(form$4 near3 recess$4) near6 "injection molding"	182	L2
L1	recess$4 near6 "injection molding"	573	L1

END OF SEARCH HISTORY

h   e   b   b   cg   b   e   e   ch